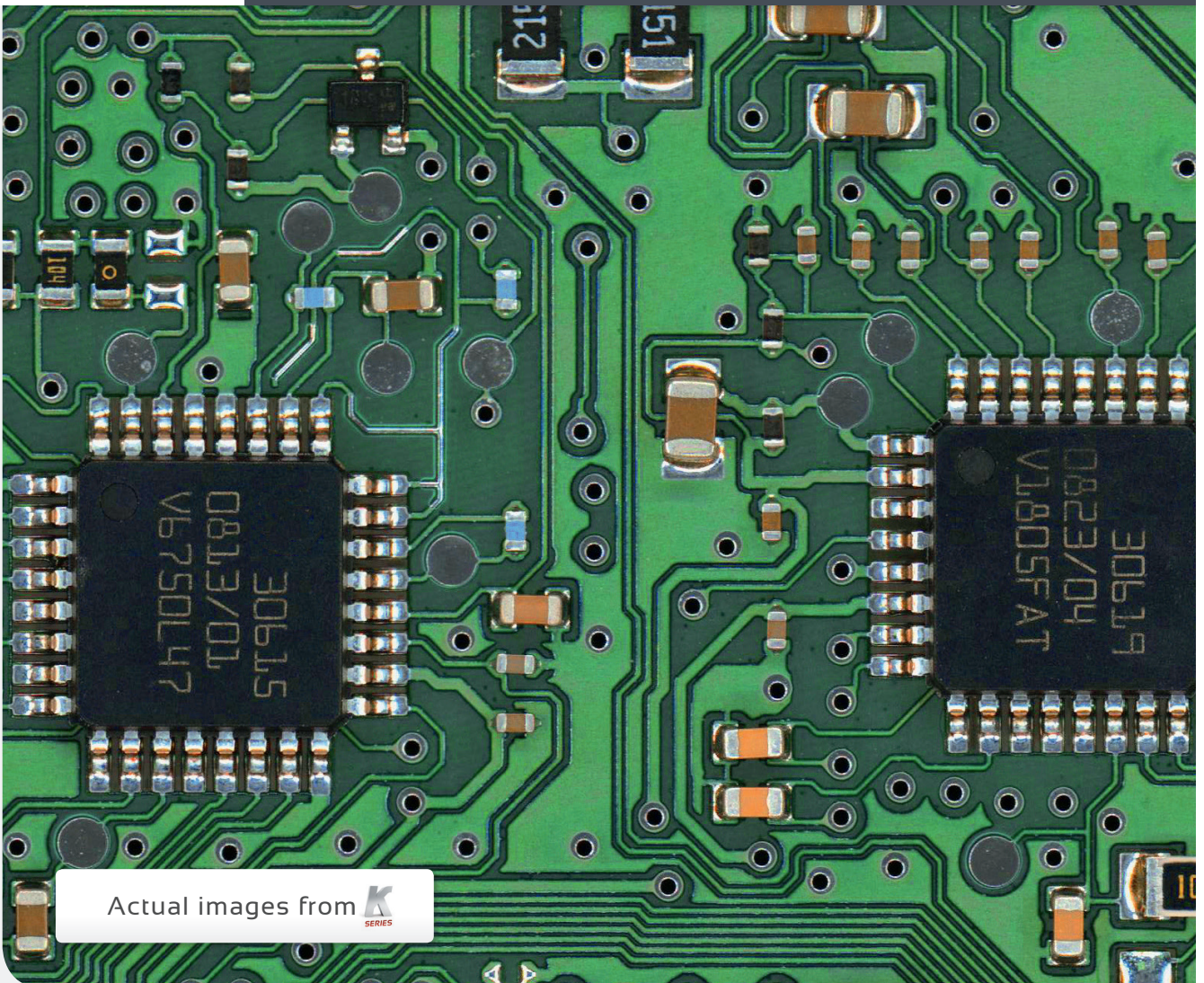




K
SERIES

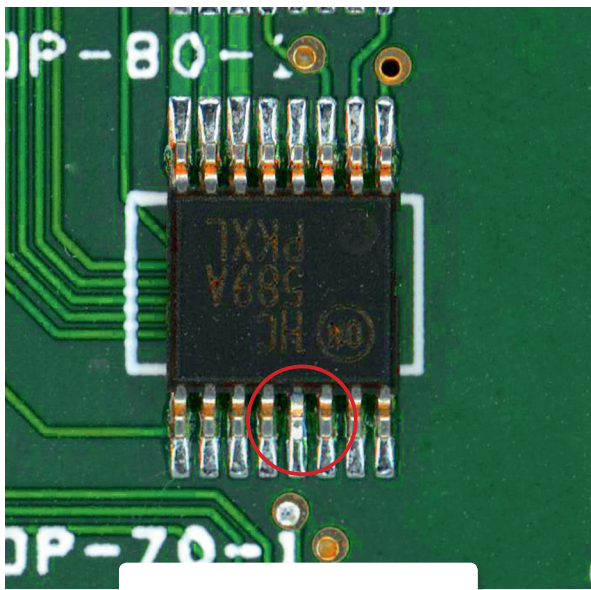
AOI

Detect & measure your true
process defects

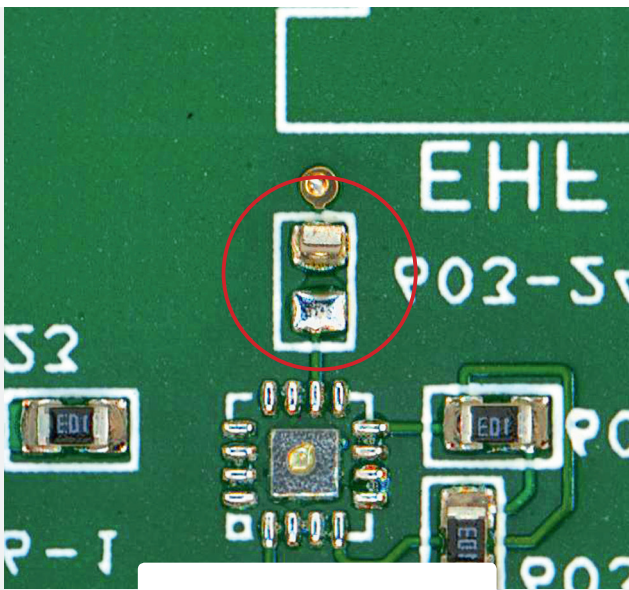


Actual images from 

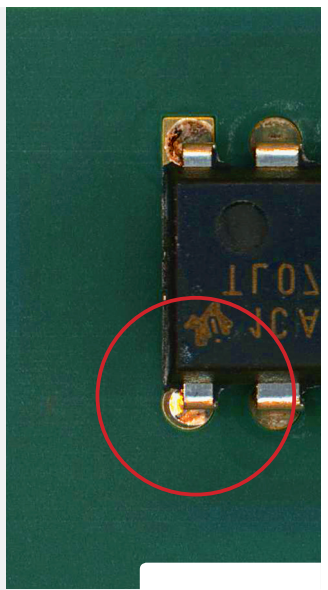
V TECHNOLOGY®



Lifted lead



Tombstone



Wettable

A product range

to meet your specific AOI needs



Coverage



Performance



Accuracy



2K

compact

Board size
14" x 14"

5K

high speed

Board size
21" x 24"

7K

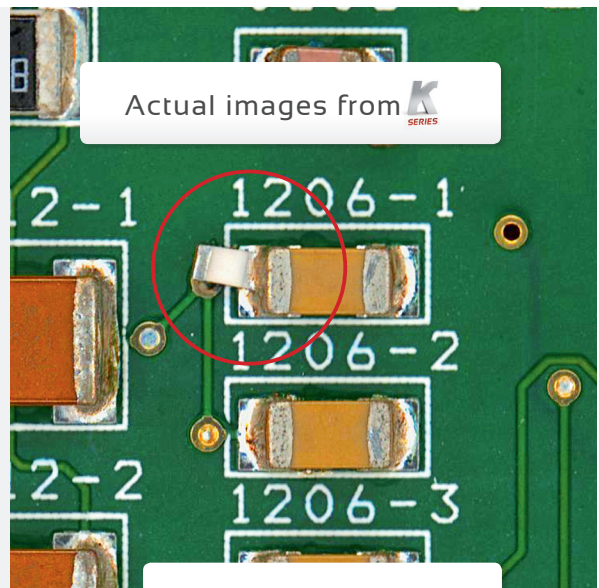
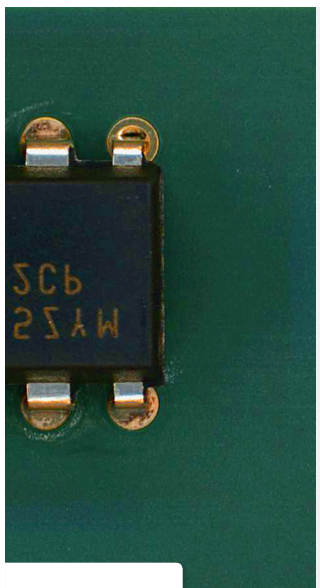
dual lane

Board size
2 x 21" x 11"

9K

extra large

Board size
40" x 24" option



Actual images from **K** SERIES

Proven defect detection



Coverage

Comprehensive defect coverage

Complete pre & post reflow, defect detection

N 3D measurements for BGA, QFP, QFN, ...

X,Y,θ measurements

Presence/absence

Polarity

Lifted lead, solder joint, bridge, insufficient, ...

Pin through hole, pin in paste

OCR, OCV



Performance

The choice of Industry leaders

Production proven, with over 3000 systems installed in 35 countries

X,Y GRR < 4% on O1005 @ +/- 50 um PTW

Low false call down to 50 ppm in production

Inspection speed up to 100 cm²/s

Fast programming time

LibraryPro to guarantee performance over time

Full program portability



Accuracy

High precision optical metrology system

N Laser option for 3D measurements

12 bit – 8 M Pixel CCD Camera

Telecentric Lens

RGB lighting with **holographic** diffuser

4,75 μm sub pixel technology

High precision **linear** motors
1 μm repeatability

Algorithm based image processing

Massive parallel processing

N New feature : 3D Selective option for Spectro



SERIES

Specifications



Technology

Camera	8 M Pixel, 12 bits CCD
Inspection resolution (Sub-pixel technology)	4.75 µm
Optics	Telecentric lens
Field of view dimensions	61.1 x 44.9 mm2 (2.40" x 1.76")
Lighting colors	SPECTRO (White, Red, Blue)
Lighting types	Axial and peripheral with holographic diffuser
Components inspected per hour	480 000
Type of components inspected	01005 up to exotic & large

Software Suite

Vision integrated software suite	Vision20
Off-line programming software	Optional
Off-line repair software	Standard
Standard Library based on JEDEC packages	Standard
Data import	Sigma Link Data Import module
Data analysis	Sigma Link Data Analysis module

Computing system

Operating system	WINDOWS XP Service Pack 3
Processor	Intel Core i5 4-Core, 4GB memory
Network	TCP/IP, RJ45 plug

PCB handling

Minimum PCB dimensions (LxW)	2" x 2"	2" x 2"	2" x 2"	2" x 2"
Maximum PCB dimensions (LxW)	14" x 14"	21" x 24"	2 x 21" x 11"	21" x 24"
				40" x 24" (option)
Board thickness	0.5 - 4 mm	0.5 - 4 mm	0.5 - 4 mm	0.5 - 15 mm
Maximum PCB weight	3 kg	3 kg	3 kg	15 kg
Minimum edge clearance	3 mm	3 mm	3 mm	5 mm
Top clearance			34 mm	
Bottom clearance			60 mm	
Board positioning			Board and panel fiducials	
XY table			Linear motors and encoders	
Frame type			Pre-stressed frame	
Conveyor width adjustment			Automatic	

Facilities

Interface	SMEMA 2 (IPC 9851)			
Power requirements	115 V / 60 Hz / 16 A, 230 V / 50 Hz / 10 A			
Transport height	870 - 970 mm			
Weight	700 kg	900 kg	900 kg	900 kg
Machine width	900 mm	1110 mm	1110 mm	1110 mm
Machine depth	900 mm	1351 mm	1351 mm	1351 mm
Machine height	1890 mm	1892 mm	1892 mm	1892 mm

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